

# SOT1350-1

plastic ultra thin fine-pitch land grid array package; 49 lands

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	UFLGA49
<b>Package type industry code</b>	UFLGA49
<b>Package style descriptive code</b>	UFLGA (ultra thin fine-pitch land grid array package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	4-6-2013

Table 1. Package summary

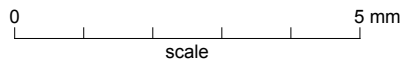
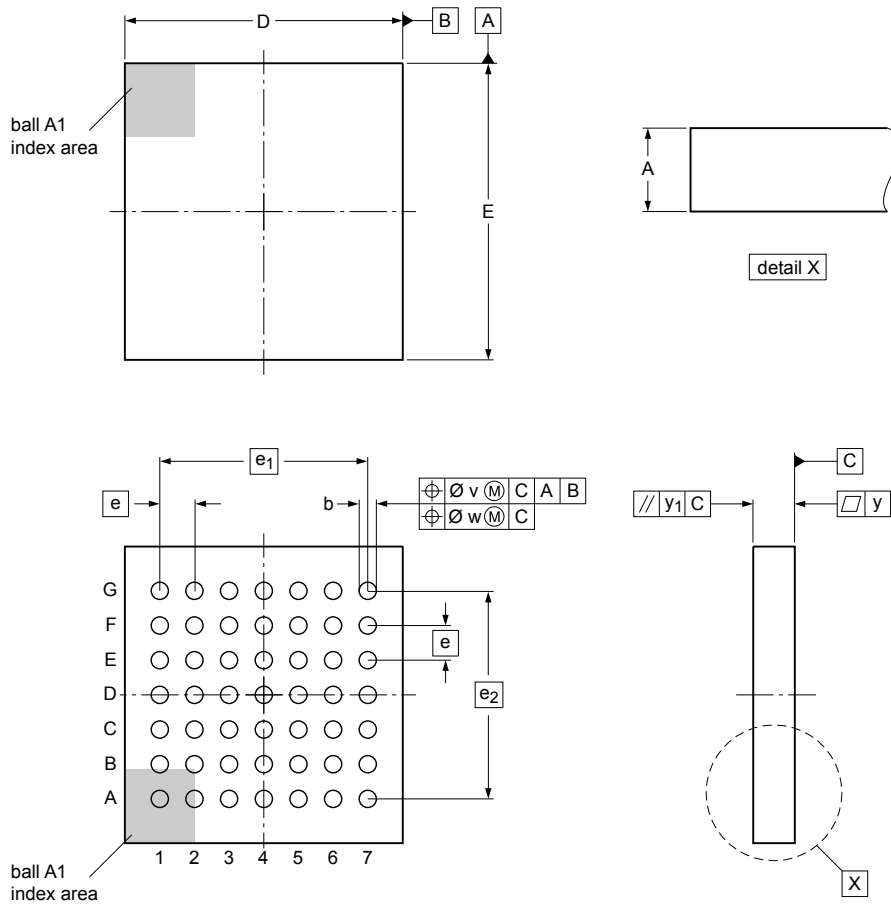
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	4.2	-	4.3	4.4	mm
A	seated height	0.55	-	0.6	0.65	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	49	-	



## 2. Package outline

UFLGA49: plastic ultra thin fine-pitch land grid array package; 49 lands

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Dimensions (mm are the original dimensions)

Unit	A	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
max	0.65	0.28	4.1	4.4							
mm nom	0.60	0.25	4.0	4.3	0.5	3.0	3.0	0.15	0.05	0.08	0.1
min	0.55	0.22	3.9	4.2							

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1350-1		---			-13-05-31- 13-06-04

Fig. 1. Package outline UFLGA49 (SOT1350-1)

### 3. Legal information

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